

Abstract of the Disclosure

It is an object to provide solid-state imaging device, which can easily be manufactured and has a high
5 reliability, and a method of manufacturing the solid-state
imaging device. In the present invention, a manufacturing
method comprises the steps of forming a plurality of IT-
CCDs on a surface of a semiconductor substrate, bonding a
translucent member to the surface of the semiconductor
10 substrate in order to have a gap opposite to each light
receiving region of the IT-CCD, and isolating a bonded
member obtained at the bonding step for each of the IT-
CCDs.